

TITLE: SLIMLINE SATA CONN. SMT TYPE

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2 SCOPE

This specification covers performance, tests and quality requirements for the slimline SATA connector series products.

P/N: 5086X /5089X/5088X/51876/51861 series.

3 APPLICABLE DOCUMENTS

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

4.1 Design and Construction

4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.

4.2 Materials and Finish

4.2.1 Contact: High performance copper alloy
Plated: [Refer to the drawing.](#)

4.2.2 Housing: [Thermoplastic, High temp. UL94V-0.](#)

4.2.3 Screw: [High performance copper alloy](#)
Plated: [Refer to the drawing.](#)

4.2.4 Board Lock: [High performance copper alloy](#)
Plated: [Refer to the drawing.](#)

4.3 Ratings

4.3.1 Voltage: [15 Volts AC](#)

4.3.2 Current: [DC 1.5 Amperes](#)

4.3.3 Operating Temperature : [-35°C to +85°C](#)

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5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.
ELECTRICAL		
Item	Requirement	Standard
Low Level Contact Resistance	30 m Ω Max.(initial)per contact 15 m Ω Max. Change allowed	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)
Insulation Resistance	1000 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 0.5 mA max.	500 VAC Min. at sea level for 1 minute. Test between adjacent contacts of mated and unmated connector assemblies (EIA-364-20)
Mated Connector Impedance (Signal Port)	100 Ω \pm 15%	<ol style="list-style-type: none"> Set the Time Domain Reflectometer (TDR) pulse in differential mode with a positive going (V+) and a negative going pulse (V-). Define a reflected differential trace: $V_{diff}=V+ - V-$ With the TDR connected to the risetime reference trace, verify an input risetime of 70 ps (measured 20% - 80% Vp). Filtering may be used to slow the system down (see NOTE 2) Connect the TDR to the sample measurement traces. Calibrate the instrument and system (see NOTE 3) Measure and record the maximum and minimum values of the near end connector impedance.
Temperature Rise	30°C Max. Change allowed	<ol style="list-style-type: none"> Mate connector: measure the temperature rise at rated current after: 1.5 A minimum Power contact. The temperature rise above ambient shall not exceed 30°C The ambient condition is still air at 25°C Wire power pins P1, P2, P8 and P9 in parallel for power Wire ground pins P4, P5, P6, P10 and P12 in parallel for return Supply 6A total DC current to the power pins in parallel, returning from the parallel ground pins (P4, P5, P6, P10 and P12)

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NOTES

1. Time domain measurement equipment allows for delay adjustment of the pulses so launch times can be synchronized. Frequency domain equipment will require the use of phase-matched fixture. The fixture skew should be verified to be < 1ps on a TDR.
2. The system rise time is to be set via equipment filtering techniques. The filter risetime is significantly close to stimulus risetime. Therefore the filter programmed equals the square root of (t_r (observed)) squared – (t_r (stimulus))squared. After filtering, verify the risetime is achieved using the risetime reference traces on the PCB fixture.
3. Calibrate the system by substituting either precision 50-ohm loads or precision air lines (also terminated in 50 ohm loads) for the test fixture. This places the calibration plane directly at the input interface of the test fixture.

MECHANICAL		
Item	Requirement	Standard
Durability	500 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 10 ± 3mm/min. (200 cycles per hour max.) (EIA-364-09)
Screw Torque	25N(2.5Kgf) Min.	Use the torque driver to fix the connector on PCB and measure the requirement torque while the housing structure breaks.
Insertion Forces (Mating Force)	30N(3.0Kgf) Max.	Measure the force necessary to mate connector assemblies at a maximum rate of 12.5mm per minute. (EIA-364-13)
Removal Force (Unmating Force)	4N(0.39Kgf) Min.	Measure the force necessary to Un-mate connector assemblies at a maximum rate of 12.5mm per minute. (EIA-364-13)
Vibration (Random)	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm(1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be

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		traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28, test condition I)
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 30 G's half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be DC 100mA maximum for all contacts. (EIA-364-27, test condition H)

ENVIRONMENTAL

Item	Requirement	Standard
Resistance to Hand Soldering Heat	Excessive pressure shall not be applied to the terminals. See Product Qualification and Test Sequence Group 8	Soldering iron : 350\pm10$^{\circ}$C Duration : 3~4 sec.
Resistance to Reflow Soldering Heat	Second Reflow process must be taken after the product temperature has down to room condition. See Product Qualification and Test Sequence Group 8	Pre Heat : 150 $^{\circ}$ C~180 $^{\circ}$ C, 60~90sec. Heat : 230 $^{\circ}$ C Min., 40sec Min. Peak Temp. : 260 $^{\circ}$ C Max, 10sec Max. Reflow number cycle : 2 times
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -40 +0/-3 $^{\circ}$ C, 30 minutes +85 +3/-0 $^{\circ}$ C, 30 minutes (EIA-364-32)
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40 $^{\circ}$ C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)
Temperature Life	See Product Qualification and Test Sequence Group 1	Subject mated connectors to temperature life at 85$^{\circ}$C for 96 hours . (EIA-364-17, Test condition III Method A)

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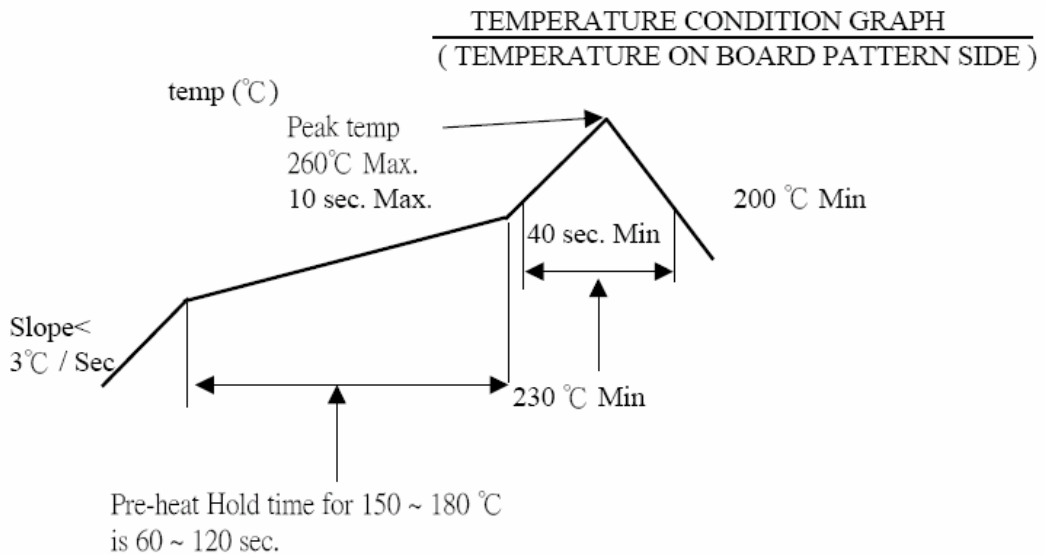
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Solder ability	Solder able area shall have minimum of 95% solder coverage.	Subject the test area of contacts into the flux for 5-10 sec. And then into solder bath, Temperature at $245 \pm 5^{\circ}\text{C}$, for 4-5 sec. (EIA-364-52)
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Note 1. Flowing Mixed Gas shall be conducted by customer request.

6 INFRARED REFLOW CONDITION



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7 PRODUCT QUALIFICATION AND TEST SEQUENCE

Test or Examination	Test Group										
	1	2	3	4	5	6	7	8	9	10	11
	Test Sequence										
Examination of Product		1、9		1、7	1、4						
Low Level Contact Resistance		3、8	1、4	2、10	2、5			1、3			
Insulation Resistance				3、9							
Dielectric Withstanding Voltage				4、8							
Temperature rise	1										
Insertion Forces		2、7									
Removal Forces		4、6									
Durability		5									
Vibration			2								
Shock (Mechanical)			3								
Thermal Shock				5							
Humidity				6							
Temperature life					3						
Solder ability							1				
Resistance to Soldering Heat								2			
Impedance (Signal Port)						1					
Sample Size	2	4	4	4	4	4	4	2	4		